

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>TAKAHIRO SENZAKI</td> <td>12/02/2013</td> </tr> <tr> <td>KEN MIYAGI</td> <td>12/02/2013</td> </tr> <tr> <td>SHIGENORI FUJIKAWA</td> <td>12/02/2013</td> </tr> <tr> <td>MARI KOIZUMI</td> <td>12/02/2013</td> </tr> <tr> <td>HARUMI HAYAKAWA</td> <td>12/02/2013</td> </tr> </tbody> </table>		Name	Execution Date	TAKAHIRO SENZAKI	12/02/2013	KEN MIYAGI	12/02/2013	SHIGENORI FUJIKAWA	12/02/2013	MARI KOIZUMI	12/02/2013	HARUMI HAYAKAWA	12/02/2013
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RECEIVING PARTY DATA													
<table border="1"> <tr> <td>Name:</td> <td>TOKYO OHKA KOGYO CO., LTD.</td> </tr> <tr> <td>Street Address:</td> <td>150, NAKAMARUKO, NAKAHARA-KU, KANAGAWA</td> </tr> <tr> <td>City:</td> <td>KAWASAKI-SHI</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>211-0012</td> </tr> </table>		Name:	TOKYO OHKA KOGYO CO., LTD.	Street Address:	150, NAKAMARUKO, NAKAHARA-KU, KANAGAWA	City:	KAWASAKI-SHI	State/Country:	JAPAN	Postal Code:	211-0012		
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<table border="1"> <tr> <td>Name:</td> <td>RIKEN</td> </tr> <tr> <td>Street Address:</td> <td>2-1, HIROSAWA, SAITAMA</td> </tr> <tr> <td>City:</td> <td>WAKO-SHI</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>351-0198</td> </tr> </table>		Name:	RIKEN	Street Address:	2-1, HIROSAWA, SAITAMA	City:	WAKO-SHI	State/Country:	JAPAN	Postal Code:	351-0198		
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PROPERTY NUMBERS Total: 1													
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CORRESPONDENCE DATA													
Fax Number:	(949)760-9502												
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<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>													
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ATTORNEY DOCKET NUMBER: SHIGA7.363APC

NAME OF SUBMITTER: NEIL S. BARTFELD

Signature: /Neil S. Bartfeld/

Date: 12/11/2013

Total Attachments: 4
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ASSIGNMENT

WHEREAS, I/WE (1) Takahiro SENZAKI
a Japanese citizen, residing at Kawasaki-shi, Japan
(2) Ken MIYAGI
a Japanese citizen, residing at Kawasaki-shi, Japan
(3) Shigenori FUJIKAWA
a Japanese citizen, residing at Wako-shi, Japan
(4) Mari KOIZUMI
a Japanese citizen, residing at Wako-shi, Japan
(5) Harumi HAYAKAWA
a Japanese citizen, residing at Wako-shi, Japan

hereinafter referred to as Assignor (collectively if more than one inventor is listed above), have invented certain new and useful improvements in

SOLVENT DEVELOPABLE NEGATIVE RESIST COMPOSITION, RESIST PATTERN FORMATION METHOD, AND

METHOD FOR FORMING PATTERN OF LAYER INCLUDING BLOCK COPOLYMER

the specification of which:

- (a) was executed on even date herewith;
- (b) was filed on _____ as Application No. _____ or Express Mail No., as Application No. not yet known _____ and was amended on _____ (if applicable); or
- (c) was described and claimed in PCT International Application No. PCT/JP2012/064811 filed on June 8, 2012 and as amended under PCT Article 19 on _____ (if any) and/or under PCT Article 34 on _____ (if any).

AND WHEREAS, (1) TOKYO OHKA KOGYO CO., LTD. and (2) RIKEN, with its principal place of business at (1) 150, Nakamaruko, Nakahara-ku, Kawasaki-shi, Kanagawa 211-0012 Japan; (2) 2-1, Hirosawa, Wako-shi, Saitama 351-0198 Japan (hereinafter referred to as Assignee) desires to acquire the entire right, title, and interest in and to the said improvements with respect to the United States of America, its territories and possessions.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, Assignor hereby acknowledges that it has sold, assigned, transferred and set over, and by these presents does hereby sell, assign, transfer and set over, unto Assignee, its successors, legal representatives and assigns, the entire right, title, and interest in the United States of America, and its territories and possessions in, to and under said improvements, and any Patent Applications in the United States of America and all divisions, renewals and continuations thereof, and all Patents of the United States of America which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions; and Assignor hereby authorizes and requests the Commissioner of Patents of the United States of America to issue all Patents for said improvements to Assignee, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND ASSIGNOR HEREBY covenants and agrees that it will communicate to Assignee, its successors, legal representatives and assigns, any facts known to it respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in the United States of America.

IN TESTIMONY WHEREOF, Assignor intending to be legally bound has hereunto affixed its signature.

24377
OSP-50135
US 護 2/2

This _____ day of _____, 2013

Signature of Takahiro SENZAKI

This _____ day of _____, 2013

Signature of Ken MIYAGI

This 2nd day of December, 2013

Shigenori Fujikawa

Signature of Shigenori FUJIKAWA

This 2nd day of December, 2013

Mari Koizumi

Signature of Mari KOIZUMI

This 2nd day of December, 2013

Harumi Hayakawa

Signature of Harumi HAYAKAWA

Witnessed by:

PF-5
H:\DOCS\KAC\KAC-1199.DOC
020503

PATENT

ASSIGNMENT

WHEREAS, I/WE (1) Takahiro SENZAKI,
a Japanese citizen, residing at Kawasaki-shi, Japan
(2) Ken MIYAGI,
a Japanese citizen, residing at Kawasaki-shi, Japan
(3) Shigenori FUJIKAWA,
a Japanese citizen, residing at Wako-shi, Japan
(4) Mari KOIZUMI,
a Japanese citizen, residing at Wako-shi, Japan
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IN TESTIMONY WHEREOF, Assignor intending to be legally bound has hereunto affixed its signature.

K201100120500
NSP50135 第2/2

This 2nd day of December, 2013

Takahiro SENZAKI
Signature of Takahiro SENZAKI

This 2nd day of December, 2013

Ken Miyagi
Signature of Ken MIYAGI

This _____ day of _____, 2013

Signature of Shigenori FUJIKAWA

This _____ day of _____, 2013

Signature of Mari KOIZUMI

This _____ day of _____, 2013

Signature of Harumi HAYAKAWA

Witnessed by:

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